

1 2 3 4 5 6

A

A

ZZ2

Assembly Note

These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3

Assembly Note

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4

Assembly Note

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

H1



Heat Sink is mounted on Top Layer

B

B

C

C

D

D

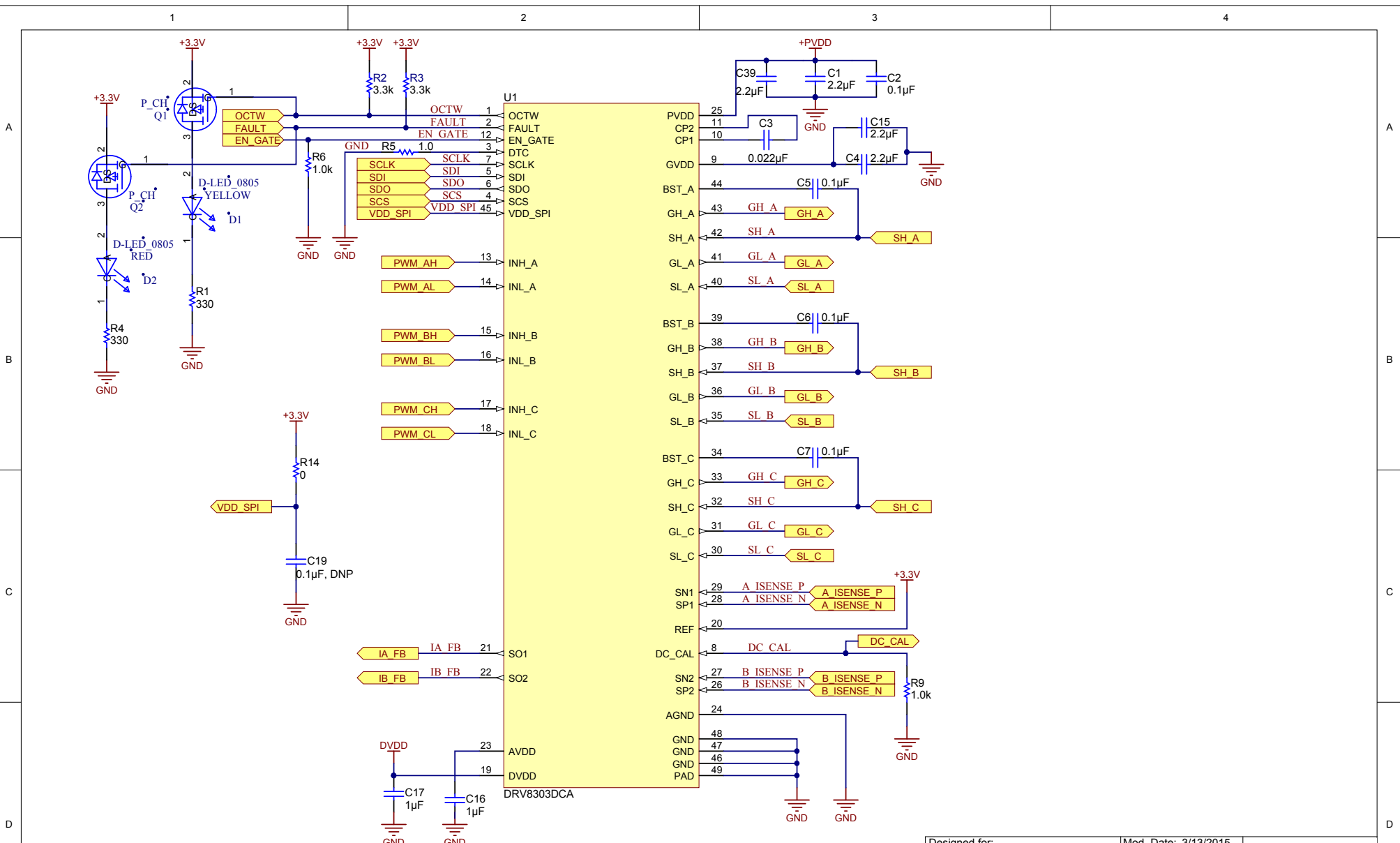
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Designed for:		Mod. Date: 3/13/2015	
Project Title: TIDA-00436 E2			
Number: TIDA-00436	Rev: E2	Sheet Title:	
SVN Rev: Not in version control	Assembly Variant: 002	Sheet: 1 of 5	
Drawn By:	File: HARDWARE_SchDoc	Size: B	
Engineer: Nelson	Contact: http://www.ti.com/support		



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1 2 3 4 5 6

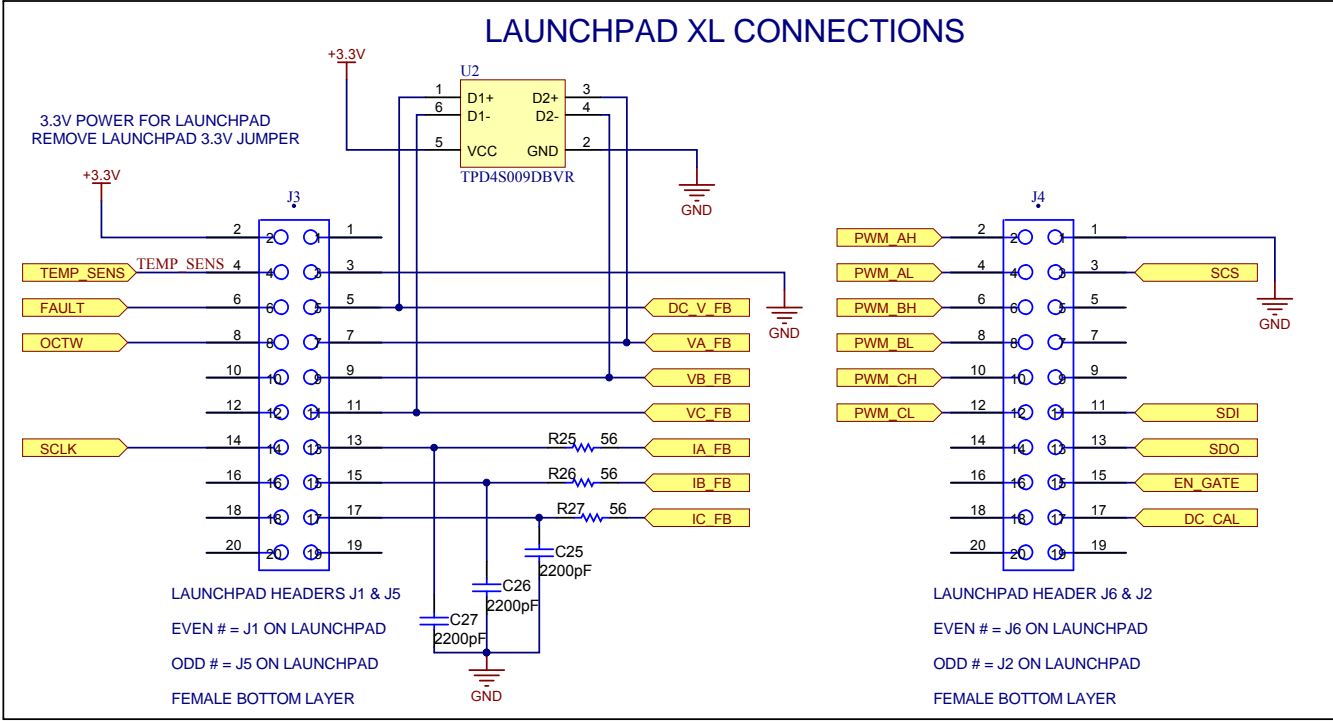
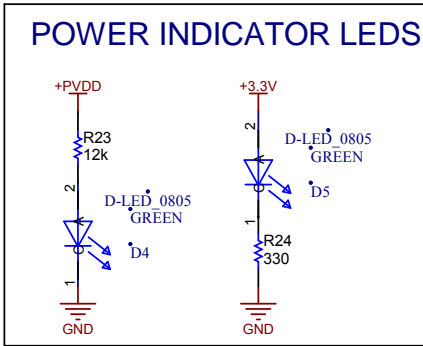
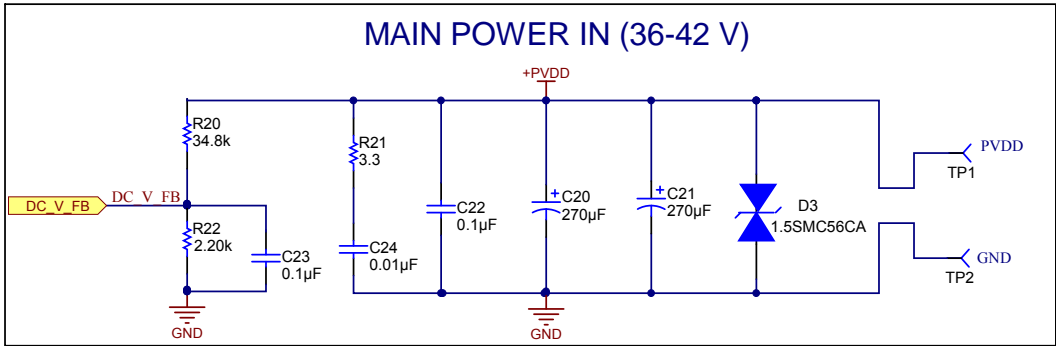


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Number: **TIDA-00436** | Rev: **E2**
 SVN Rev: Not in version control
 Drawn By:
 Engineer: **Nelson**

Designed for: | Mod. Date: 3/13/2015
 Project Title: **TIDA-00436_E2**
 Sheet Title:
 Assembly Variant: **002** | Sheet: **1** of **5**
 File: **DRV8303.SchDoc** | Size: **A4**
 Contact: <http://www.ti.com/support>



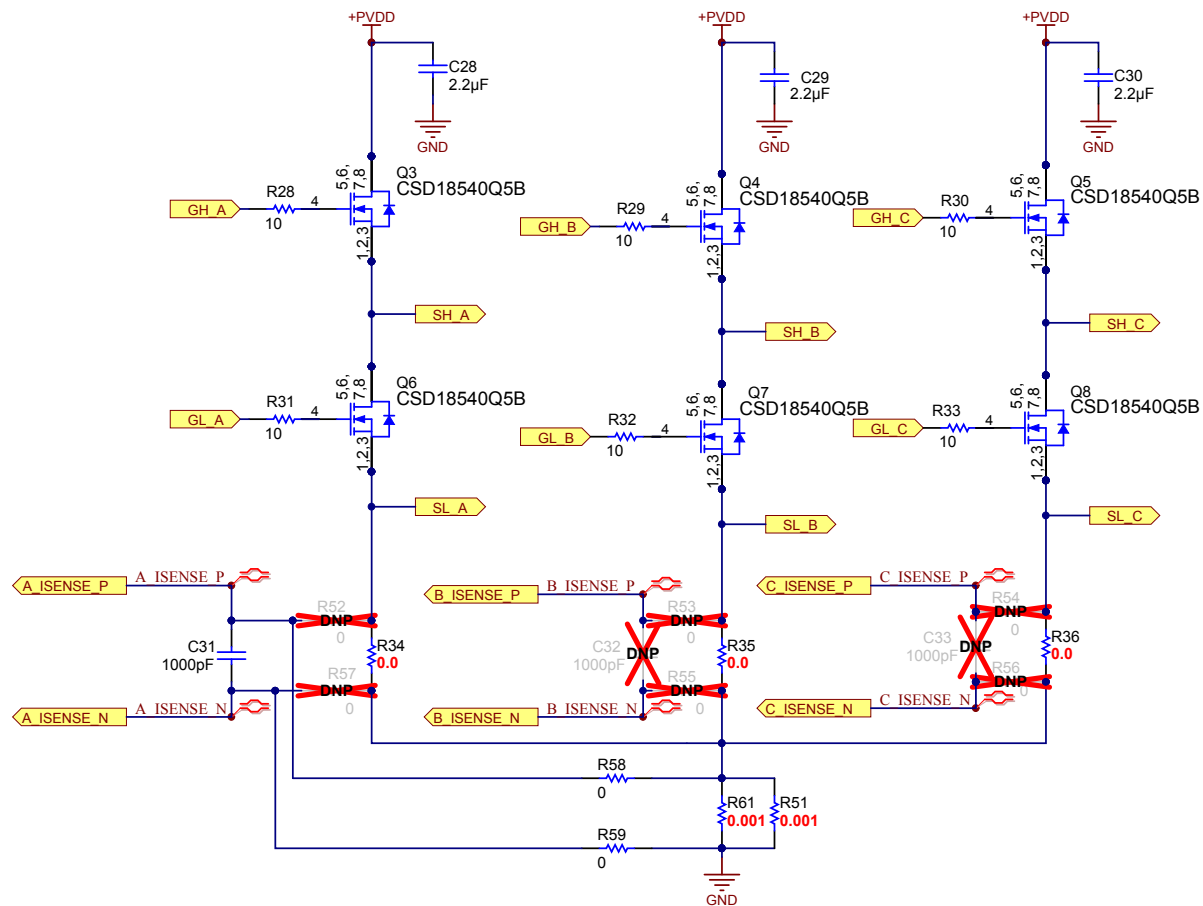


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Number: TIDA-00436 | Rev: E2
 SVN Rev: Not in version control
 Drawn By:
 Engineer: Nelson

Designed for:	Mod. Date: 3/13/2015
Project Title: TIDA-00436 E2	
Sheet Title:	
Assembly Variant: 002	Sheet: 2 of 5
File: LAUNCHPAD.SchDoc	Size: A4
Contact: http://www.ti.com/support	





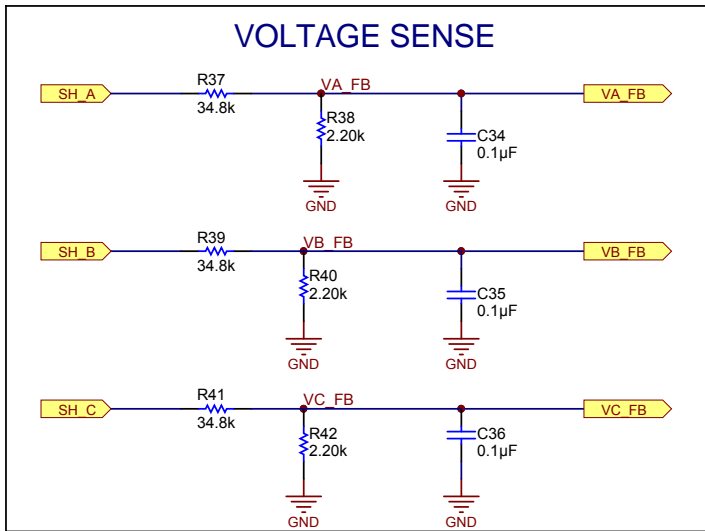
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Number: TIDA-00436 | Rev: E2
 SVN Rev: Not in version control
 Drawn By:
 Engineer: Nelson

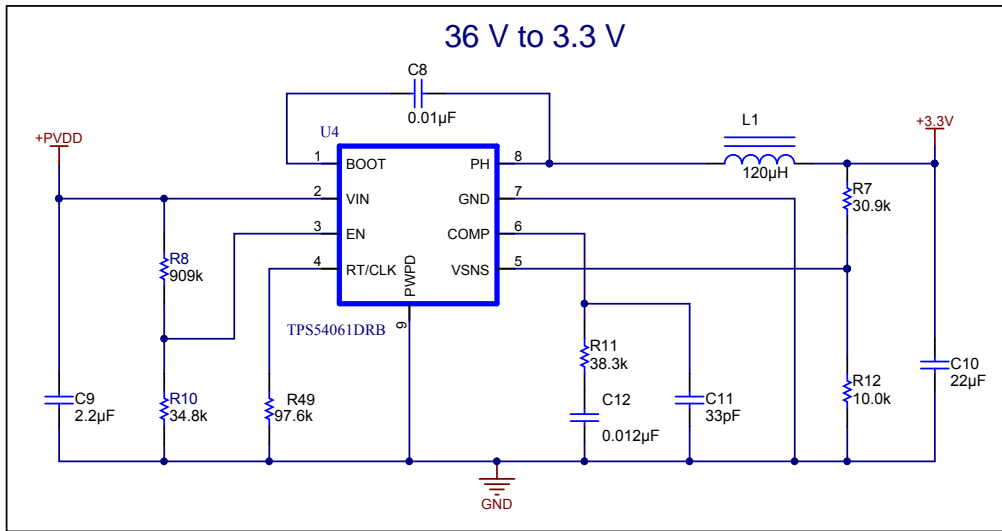
Designed for: | Mod. Date: 3/13/2015
 Project Title: TIDA-00436_E2
 Sheet Title:
 Assembly Variant: 002 | Sheet 3 of 5
 File: MOTOR.SchDoc | Size: A4
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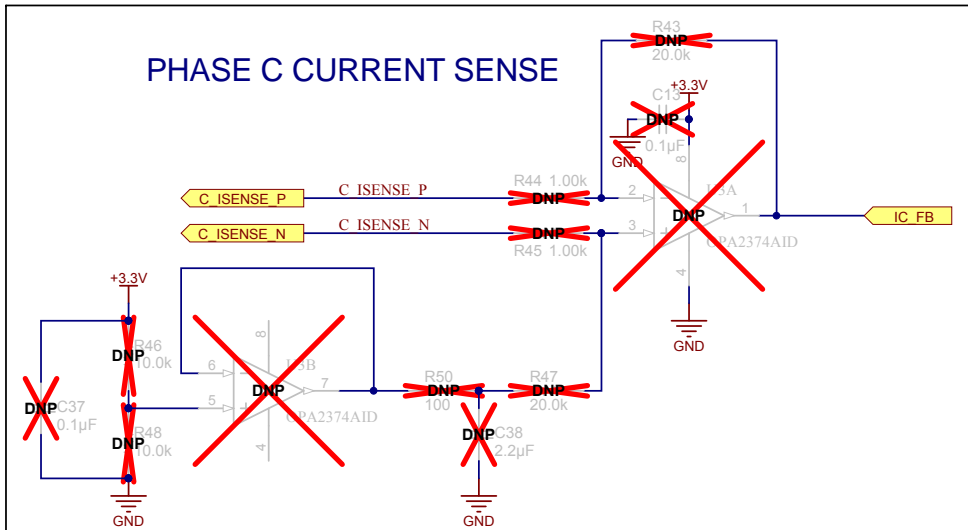
VOLTAGE SENSE



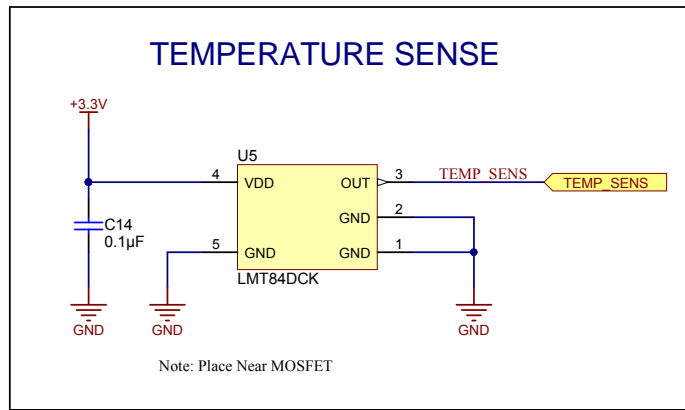
36 V to 3.3 V



PHASE C CURRENT SENSE



TEMPERATURE SENSE



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Number: TIDA-00436 Rev: E2
 SVN Rev: Not in version control
 Drawn By:
 Engineer: Nelson

Designed for: Mod. Date: 3/13/2015
 Project Title: TIDA-00436 E2
 Sheet Title:
 Assembly Variant: 002 Sheet: 4 of 5
 File: SENSE_SchDoc Size: A4
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